ALLIANCE MEMORY MDS REPORT

Part Number:		AS4C128M16D3LG-12BCN			
Part Weight:		**159.176mg**			
Item	**Material**	**Weight (mg)**	**Content**	**CAS No.**	**Percentage %**
1	Molding Compound	61.1850	Epoxy Resin	Trade secret	5.00%
			2,2'-((3,3',5,5'-tetramethyl-(1,1'-biphenyl)-4,4'-diyl)-bis(oxymethylene))-	Trade secret	2.50%
			Hardener 1	Trade secret	2.50%
			Hardener 2	Trade secret	2.50%
			Carbon black	1333-86-4	0.40%
			Amorphous Silica	60676-86-0	84.10%
			Quartz (SiO2)	14808-60-7	3.00%
2	Die Attach	1.2740	2-(2-Ethoxyethoxy)ethyl acetate	112-15-2	36.50%
			Butadiene, acrylonitrile polymer, carboxy-terminated, polymer with bisphenol A and e ichloroh drin	68610-41-3	28.00%
			Isodecyl alcohol, ethoxylated	61827-42-7	10.00%
			Silica Filler	112926-00-8	25.00%
			Tert-butyl peroxyneodecanoate	26748-41-4	0.50%
3	Substrate	50.0000	Barium Sulfate	7727-43-7	28.67%
			Continuous Filament Fiber Glass	65997-17-3	22.40%
			Copper Foil	7440-50-8	23.83%
			Cured Thermosetting Resin	Trade Secret	8.80%
			Dipropylene Glycol Monomethyl Ether	34590-94-8	7.00%
			Morpholine derivative	Trade Secret	4.80%
			Talc containing no asbestiform fibers	14807-96-6	4.50%
4	Solder Ball	33.8780	Tin (Sn)	7440-31-5	96.50%
			Silver (Ag)	7440-22-4	3.00%
			Copper (Cu)	7440-50-8	0.50%
5	Bonding Wire	0.2450	Gold (Au)	7440-57-5	99.00%
			Palladium	7440-05-3	1.00%
6	Chip	12.5940	Silicon	7440-21-3	99.00%
			Others	N/A	1.00%
Total		159.1760			mg

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Fax: 425-896-8628 Alliance Memory Inc. reserves the right to change products or specification without notice